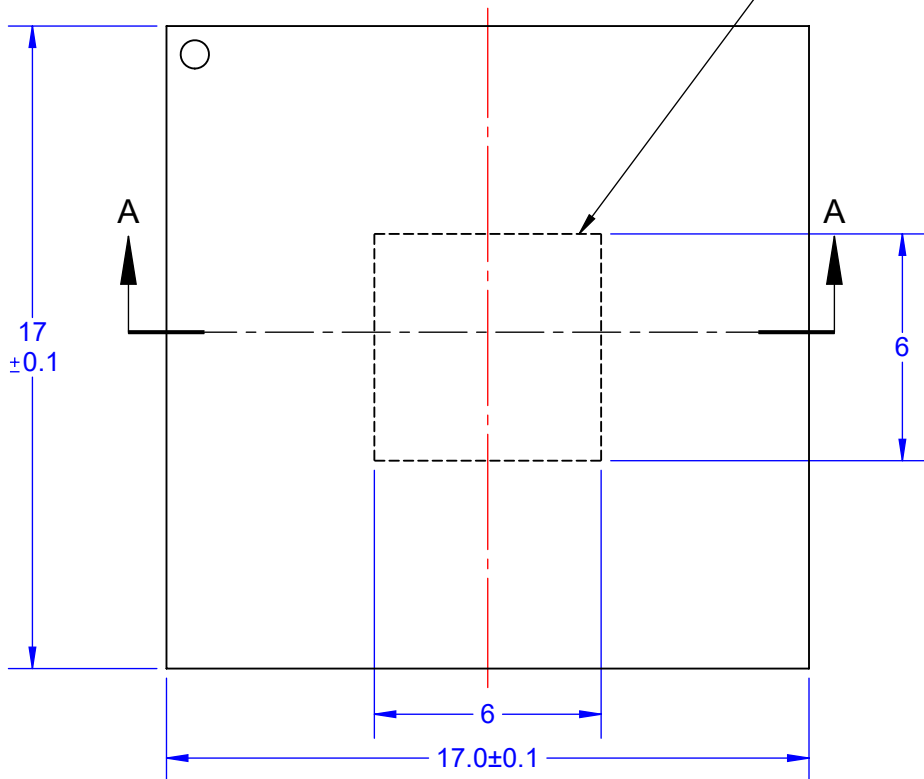


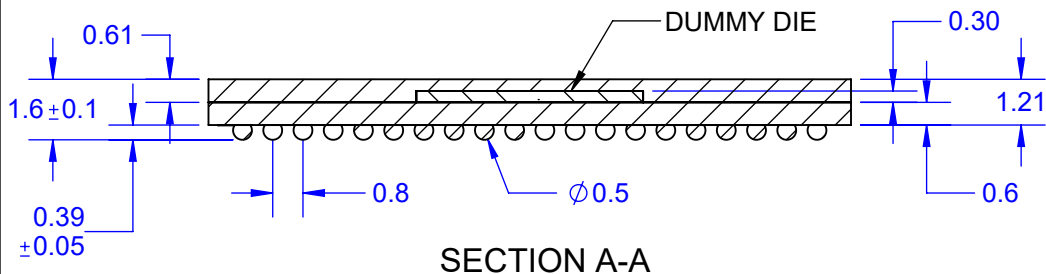
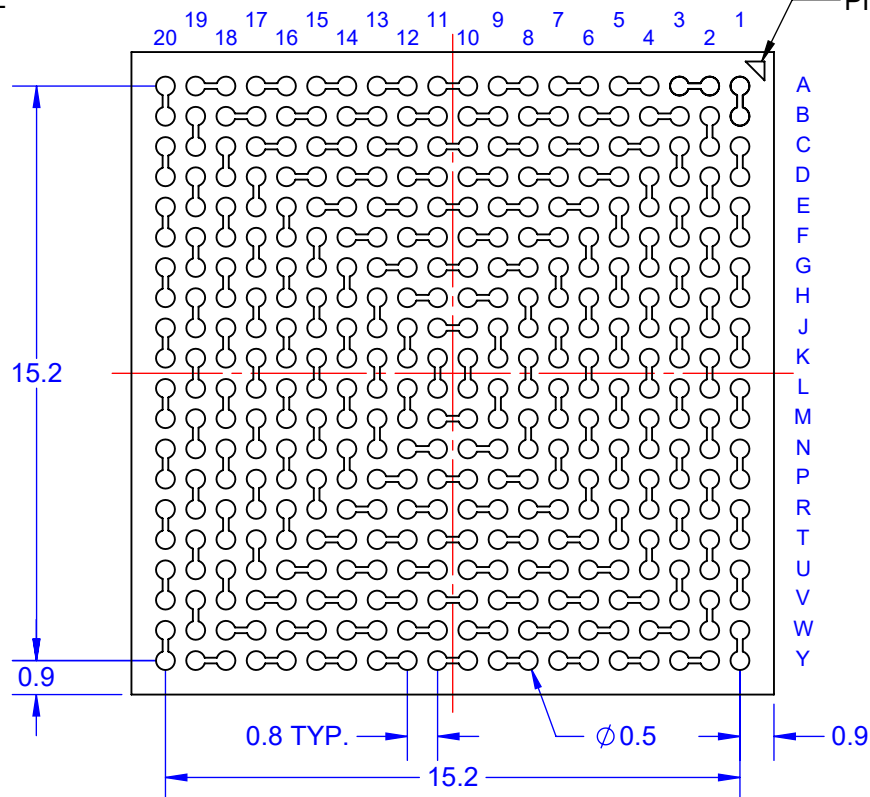
HCD J-9K

DUMMY DIE



65 @ J-9K


PIN A1



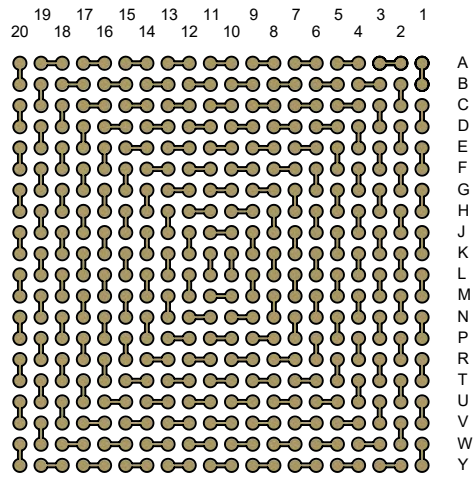
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW):  $\phi 0.50\text{mm}$  (19.7mil).
- 4) SOLDER MASK DEFINED PAD OPENING:  $\phi 0.406\text{mm}$  (16mil).
- 5) PAD Cu DIAMETER:  $\phi 0.50\text{mm}$  (19.7mil).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN ATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

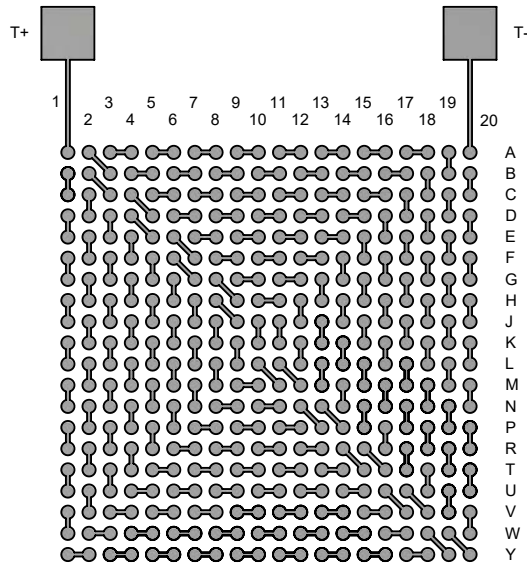
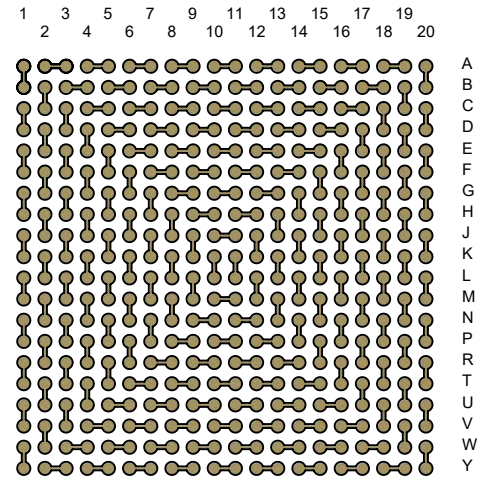
D5 FH'BI A69F H56 @				
D5 FH'BI A69F	65 @ @5 @CM	65 @ @7 C89	Fc < G	Gj'8 @
BGA400T.8C-DC209D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA400T.8-DC209D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T.Au	6/10/2021				
ENG M. Hart	6/10/2021	TITLE BGA400T.8-DC209D DAISY CHAIN DUMMY			
MFG		SCALE 5:1	SIZE A	DRAWING NO. 582093	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

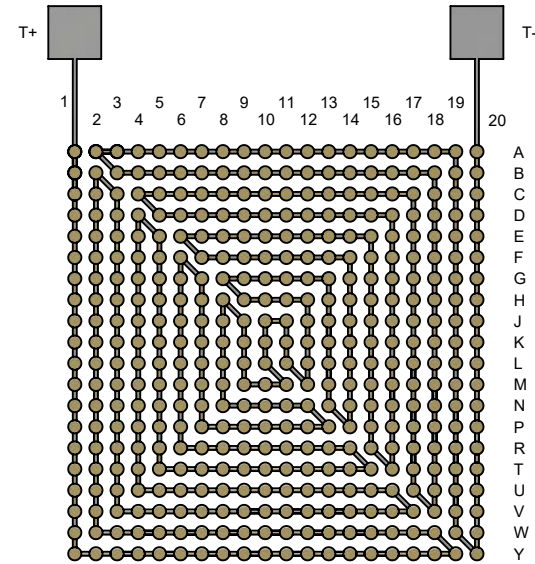
65 @@J=K



6 CHCA 'G=89 'fHCD'L!F5 MJ=K L



H9GH'J9<=7 @'6 C5 F8



5: H9F'ACI BH=B;

Notes:

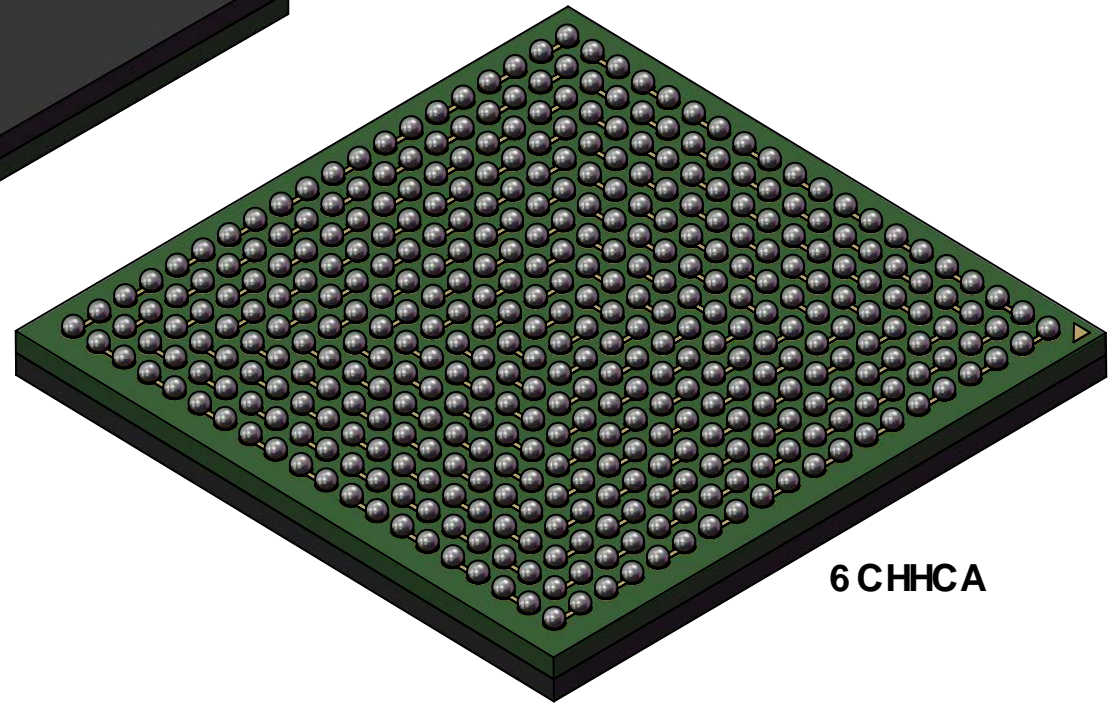
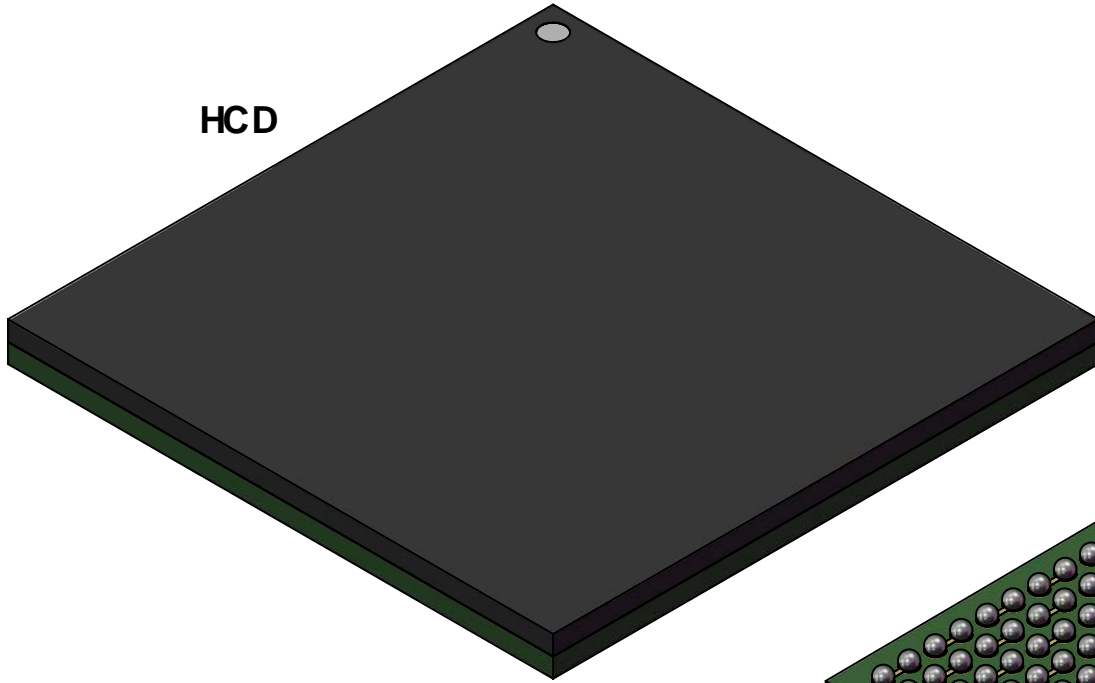
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.  
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER  $\phi$ 0.50mm (19.7mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.150 [ 6mil ].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING  $\phi$ 0.406mm (16mil).

**TopLine®**

TITLE			
BGA400T.8-DC209D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	582093	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

AC89@

HCD



6 CHCA

**TopLine<sup>®</sup>**

TITLE BGA400T.8-DC209D  
DAISY CHAIN DUMMY

SCALE 6:1	SIZE A	DRAWING NO. 582093	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3